

## 300mA CMOS LDO with Shutdown and $V_{REF}$ Bypass

### Features

- Extremely Low Supply Current (50 $\mu$ A, Typ.)
- Very Low Dropout Voltage
- 300mA Output Current
- Adjustable Output Voltages
- Power Saving Shutdown Mode
- Bypass Input for Ultra Quiet Operation
- Over Current and Over Temperature Protection
- Space-Saving MSOP Package Option

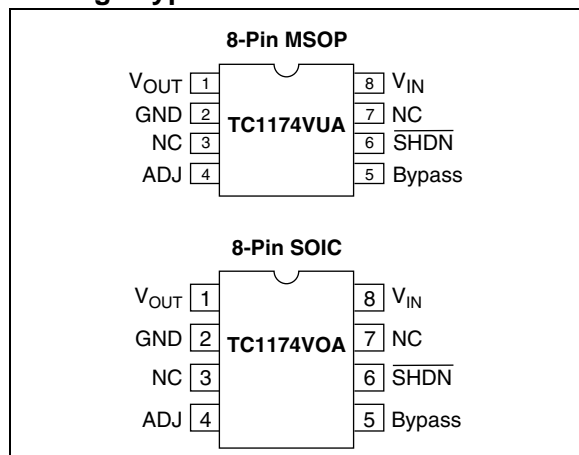
### Applications

- Battery Operated Systems
- Portable Computers
- Medical Instruments
- Instrumentation
- Cellular/GSM/PHS Phones
- Linear Post-Regulators for SMPS
- Pagers

### Device Selection Table

Part Number	Output Voltage (V)	Package	Junction Temp. Range
TC1174VOA	Adjustable	8-Pin SOIC	-40°C to +125°C
TC1174VUA	Adjustable	8-Pin MSOP	-40°C to +125°C

### Package Type



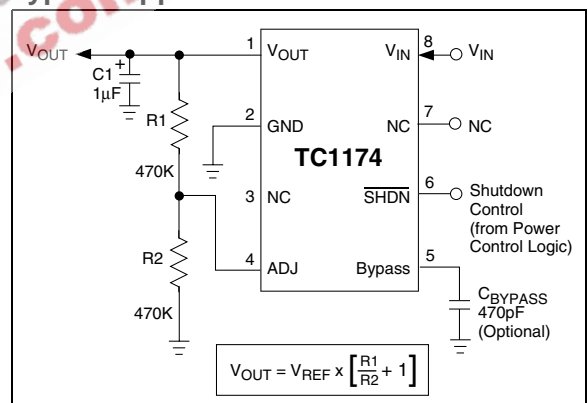
### General Description

The TC1174 is an adjustable output CMOS low dropout regulator. Total supply current is typically 50 $\mu$ A at full load (20 to 60 times lower than in bipolar regulators).

TC1174 key features include ultra low noise operation (plus optional Bypass input); very low dropout voltage (typically 270mV at full load) and internal feed-forward compensation for fast response to step changes in load. Supply current is reduced to 0.05 $\mu$ A (typical) and  $V_{OUT}$  falls to zero when the shutdown input is low.

The TC1174 incorporates both over temperature and over current protection. The TC1174 is stable with an output capacitor of only 1 $\mu$ F and has a maximum output current of 300mA.

### Typical Application



# TC1174

## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings\*

Input Voltage .....6.5V  
 Output Voltage..... (V<sub>SS</sub> – 0.3V) to (V<sub>IN</sub> + 0.3V)  
 Power Dissipation.....Internally Limited (**Note 5**)  
 Maximum Voltage on Any Pin ..... V<sub>IN</sub> +0.3V to -0.3V  
 Operating Temperature Range..... -40°C < T<sub>J</sub> < 125°C  
 Storage Temperature..... -65°C to +150°C

\*Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

### TC1174 ELECTRICAL SPECIFICATIONS

<b>Electrical Characteristics:</b> V <sub>IN</sub> = V <sub>OUT</sub> + 1V, I <sub>L</sub> = 0.1μA, C <sub>L</sub> = 3.3μF, $\overline{\text{SHDN}} > V_{IH}$ , T <sub>A</sub> = 25°C, unless otherwise noted. <b>Boldface</b> type specifications apply for junction temperatures of -40°C to +125°C.						
Symbol	Parameter	Min	Typ	Max	Units	Test Conditions
V <sub>IN</sub>	Input Operating Voltage	<b>2.7</b>	—	<b>6.0</b>	V	<b>Note 6</b>
I <sub>OUTMAX</sub>	Maximum Output Current	<b>300</b>	—	—	mA	
V <sub>REF</sub>	Reference Voltage	<b>1.165</b>	1.20	<b>1.235</b>	V	
ΔV <sub>OUT</sub> /ΔT	V <sub>OUT</sub> Temperature Coefficient	—	<b>40</b>	—	ppm/°C	<b>Note 1</b>
ΔV <sub>OUT</sub> /ΔV <sub>IN</sub>	Line Regulation	—	0.05	<b>0.35</b>	%	(V <sub>R</sub> + 1V) ≤ V <sub>IN</sub> ≤ 6V
ΔV <sub>OUT</sub> /V <sub>OUT</sub>	Load Regulation	—	1.1	<b>2.0</b>	%	I <sub>L</sub> = 0.1mA to I <sub>OUTMAX</sub> ( <b>Note 2</b> )
V <sub>IN</sub> -V <sub>OUT</sub>	Dropout Voltage	—	20 80 270	<b>30</b> <b>160</b> <b>480</b>	mV	I <sub>L</sub> = 0.1mA I <sub>L</sub> = 100mA I <sub>L</sub> = 300mA ( <b>Note 3</b> )
I <sub>SS1</sub>	Supply Current	—	<b>50</b>	<b>90</b>	μA	$\overline{\text{SHDN}} = V_{IH}$
I <sub>SS2</sub>	Shutdown Supply Current	—	0.05	0.5	μA	$\overline{\text{SHDN}} = 0V$
PSRR	Power Supply Rejection Ratio	—	60	—	dB	F <sub>RE</sub> = 1kHz
I <sub>OUTSC</sub>	Output Short Circuit Current	—	550	650	mA	V <sub>OUT</sub> = 0V
ΔV <sub>OUT</sub> /ΔP <sub>D</sub>	Thermal Regulation	—	0.04	—	V/W	<b>Note 4</b>
eN	Output Noise	—	260	—	nV/√Hz	F = 10kHz, I <sub>L</sub> = I <sub>OUTMAX</sub> 470pF from Bypass to GND
<b>SHDN Input</b>						
V <sub>IH</sub>	$\overline{\text{SHDN}}$ Input High Threshold	<b>45</b>	—	—	%V <sub>IN</sub>	
V <sub>IL</sub>	$\overline{\text{SHDN}}$ Input Low Threshold	—	—	<b>15</b>	%V <sub>IN</sub>	
<b>ADJ Input</b>						
I <sub>ADJ</sub>	Adjustable Input Leakage Current	—	50	—	pA	

1:  $TC V_{OUT} = \frac{(V_{OUTMAX} - V_{OUTMIN}) \times 10^6}{V_{OUT} \times \Delta T}$

- Regulation is measured at a constant junction temperature using low duty cycle pulse testing. Load regulation is tested over a load range from 0.1mA to the maximum specified output current. Changes in output voltage due to heating effects are covered by the thermal regulation specification.
- Dropout voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value measured at a 1V differential.
- Thermal Regulation is defined as the change in output voltage at a time T after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a current pulse equal to I<sub>LMAX</sub> at V<sub>IN</sub> = 6V for T = 10 msec.
- The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction-to-air (i.e., T<sub>A</sub>, T<sub>J</sub>, θ<sub>JA</sub>). Exceeding the maximum allowable power dissipation causes the device to initiate thermal shutdown. Please see Section 4.0 Thermal Considerations for more details.
- The minimum V<sub>IN</sub> has to justify the conditions: V<sub>IN</sub> ≥ V<sub>R</sub> + V<sub>DROPOUT</sub> and V<sub>IN</sub> ≥ 2.7V for I<sub>L</sub> = 0.1mA to I<sub>OUTMAX</sub>.

## 2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

**TABLE 2-1: PIN FUNCTION TABLE**

Pin No. (8-Pin SOIC) (8-Pin MSOP)	Symbol	Description
1	$V_{OUT}$	Regulated voltage output.
2	GND	Ground terminal.
3	NC	No connect.
4	ADJ	Output voltage adjust terminal. Output voltage setting is programmed with a resistor divider from $V_{OUT}$ to this input. A capacitor may also be added to this input to reduce output noise.
5	Bypass	Reference bypass input. Connecting a 470pF to this input further reduces output noise.
6	$\overline{\text{SHDN}}$	Shutdown control input. The regulator is fully enabled when a logic high is applied to this input. The regulator enters shutdown when a logic low is applied to this input. During shutdown, output voltage falls to zero and supply current is reduced to 0.05 $\mu$ A (typical).
7	NC	No connect.
8	$V_{IN}$	Unregulated supply input.

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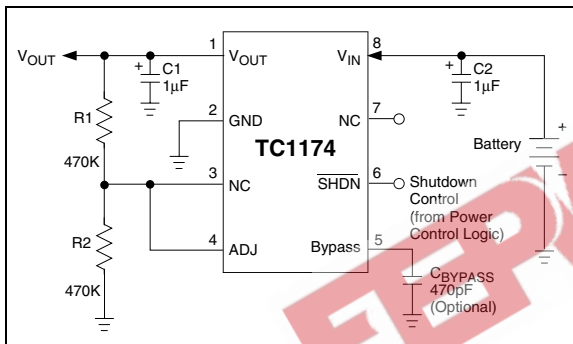
# TC1174

## 3.0 DETAILED DESCRIPTION

The TC1174 is an adjustable low drop-out regulator. Unlike bipolar regulators, the TC1174's supply current does not increase with load current. In addition,  $V_{OUT}$  remains stable and within regulation over the entire 0mA to  $I_{OUTMAX}$  operating load current range, (an important consideration in RTC and CMOS RAM battery back-up applications).

Figure 3-1 shows a typical application circuit. The regulator is enabled any time the shutdown input (SHDN) is at or above  $V_{IH}$ , and shutdown (disabled) when SHDN is at or below  $V_{IL}$ . SHDN may be controlled by a CMOS logic gate, or I/O port of a microcontroller. If the SHDN input is not required, it should be connected directly to the input supply. While in shutdown, supply current decreases to 0.05 $\mu$ A (typical),  $V_{OUT}$  falls to zero.

**FIGURE 3-1: TYPICAL APPLICATION CIRCUIT**



## 3.1 Bypass Input

A 470pF capacitor connected from the Bypass input to ground reduces noise present on the internal reference, which in turn significantly reduces output noise. If output noise is not a concern, this input may be left unconnected. Larger capacitor values may be used, but results in a longer time period to rated output voltage when power is initially applied.

## 3.2 Output Capacitor

A 1 $\mu$ F (min) capacitor from  $V_{OUT}$  to ground is required. The output capacitor should have an effective series resistance greater than 0.1 $\Omega$  and less than 5.0 $\Omega$ . A 1 $\mu$ F capacitor should be connected from  $V_{IN}$  to GND if there is more than 10 inches of wire between the regulator and the AC filter capacitor, or if a battery is used as the power source. Aluminum electrolytic or tantalum capacitor types can be used. (Since many aluminum electrolytic capacitors freeze at approximately -30°C, solid tantalums are recommended for applications operating below -25°C.) When operating from sources other than batteries, supply-noise rejection and transient response can be improved by increasing the value of the input and output capacitors and employing passive filtering techniques.

## 3.3 Adjust Input

The output voltage setting is determined by the values of R1 and R2 (Figure 3-1). The ohmic values of these resistors should be between 470K and 3M to minimize bleeder current.

The output voltage setting is calculated using the following equation.

**EQUATION 3-1:**

$$V_{OUT} = V_{REF} \times \left[ \frac{R1}{R2} + 1 \right]$$

The voltage adjustment range of the TC1174 is from  $V_{REF}$  to  $(V_{IN} - 0.05V)$ .

## 4.0 THERMAL CONSIDERATIONS

### 4.1 Thermal Shutdown

Integrated thermal protection circuitry shuts the regulator off when die temperature exceeds 150°C. The regulator remains off until the die temperature drops to approximately 140°C.

### 4.2 Power Dissipation

The amount of power the regulator dissipates is primarily a function of input and output voltage, and output current. The following equation is used to calculate worst case actual power dissipation:

#### EQUATION 4-1:

$$P_D \approx (V_{INMAX} - V_{OUTMIN})I_{LOADMAX}$$

Where:

$P_D$  = Worst case actual power dissipation  
 $V_{INMAX}$  = Maximum voltage on  $V_{IN}$   
 $V_{OUTMIN}$  = Minimum regulator output voltage  
 $I_{LOADMAX}$  = Maximum output (load) current

The maximum allowable power dissipation (Equation 4-2) is a function of the maximum ambient temperature ( $T_{AMAX}$ ), the maximum allowable die temperature ( $T_{JMAX}$ ) and the thermal resistance from junction-to-air ( $\theta_{JA}$ ). The 8-Pin SOIC package has a  $\theta_{JA}$  of approximately 160°C/Watt, while the 8-Pin MSOP package has a  $\theta_{JA}$  of approximately 200°C/Watt.

#### EQUATION 4-2:

$$P_{DMAX} = \frac{(T_{JMAX} - T_{AMAX})}{\theta_{JA}}$$

Where all terms are previously defined.

Equation 4-1 can be used in conjunction with Equation 4-2 to ensure regulator thermal operation is within limits. For example:

Given:

$V_{INMAX} = 3.0V + 10\%$   
 $V_{OUTMIN} = 2.7V - 0.5\%$   
 $I_{LOADMAX} = 250mA$   
 $T_{JMAX} = 125^\circ C$   
 $T_{AMAX} = 55^\circ C$   
 8-Pin MSOP Package

Find: 1. Actual power dissipation  
 2. Maximum allowable dissipation

Actual power dissipation:

$$P_D \approx (V_{INMAX} - V_{OUTMIN})I_{LOADMAX}$$

$$= [(3.0 \times 1.1) - (2.7 \times .995)]250 \times 10^{-3}$$

$$= 155mW$$

Maximum allowable power dissipation:

$$P_{DMAX} = \frac{(T_{JMAX} - T_{AMAX})}{\theta_{JA}}$$

$$= \frac{(125 - 55)}{200}$$

$$= 350mW$$

In this example, the TC1174 dissipates a maximum of 155mW; below the allowable limit of 350mW. In a similar manner, Equation 4-1 and Equation 4-2 can be used to calculate maximum current and/or input voltage limits. For example, the maximum allowable  $V_{IN}$  is found by substituting the maximum allowable power dissipation of 350mW into Equation 4-1, from which  $V_{INMAX} = 4.1V$ .

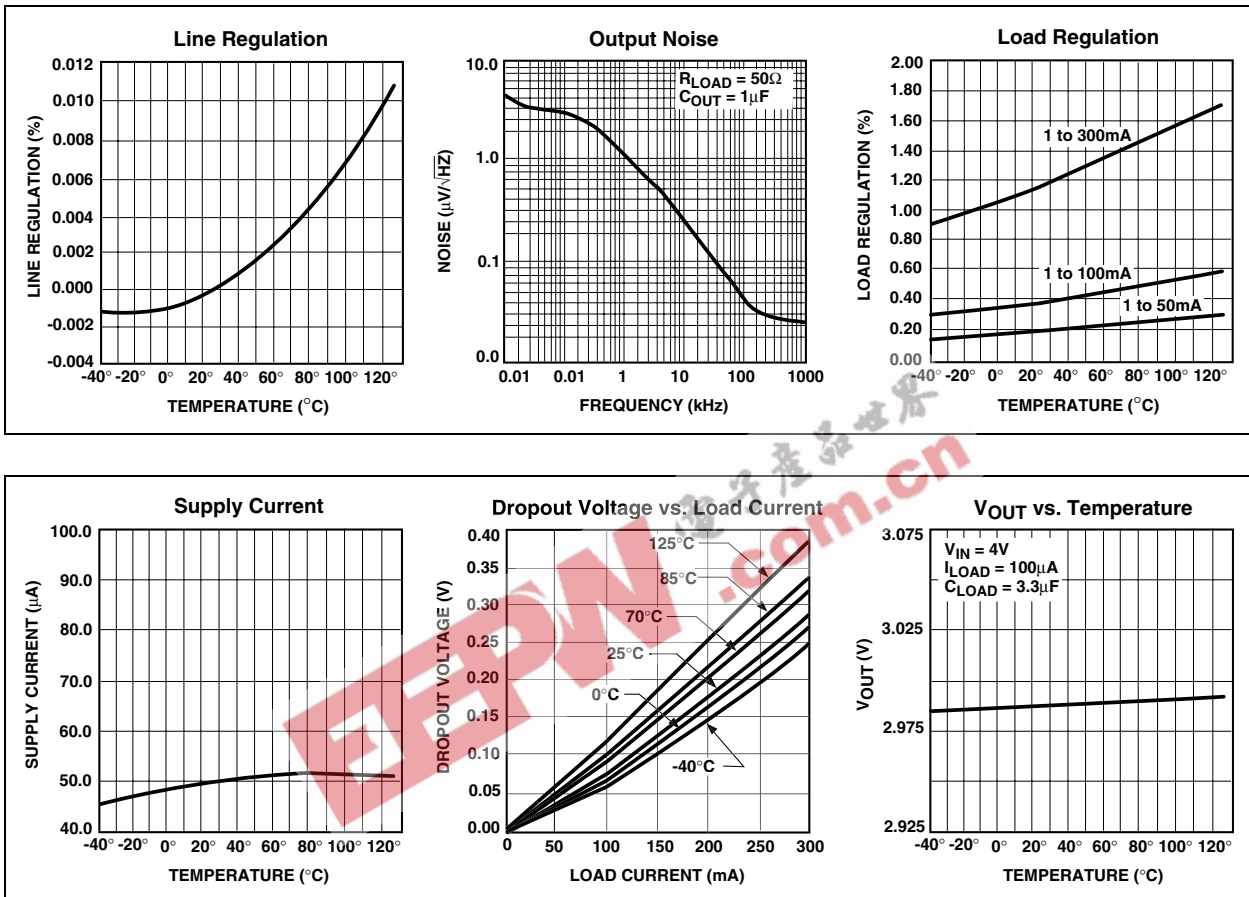
### 4.3 Layout Considerations

The primary path of heat conduction out of the package is via the package leads. Therefore, layouts having a ground plane, wide traces at the pads, and wide power supply bus lines combine to lower  $\theta_{JA}$  and therefore increase the maximum allowable power dissipation limit.

# TC1174

## 5.0 TYPICAL CHARACTERISTICS

**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

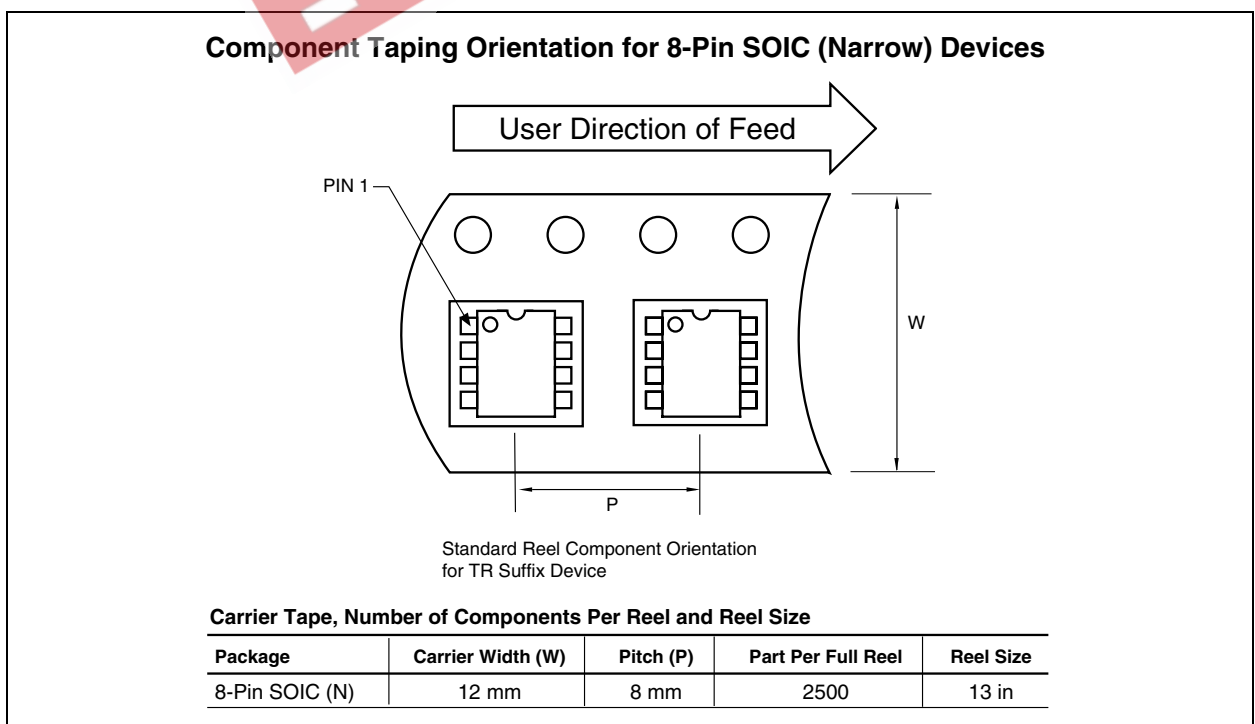
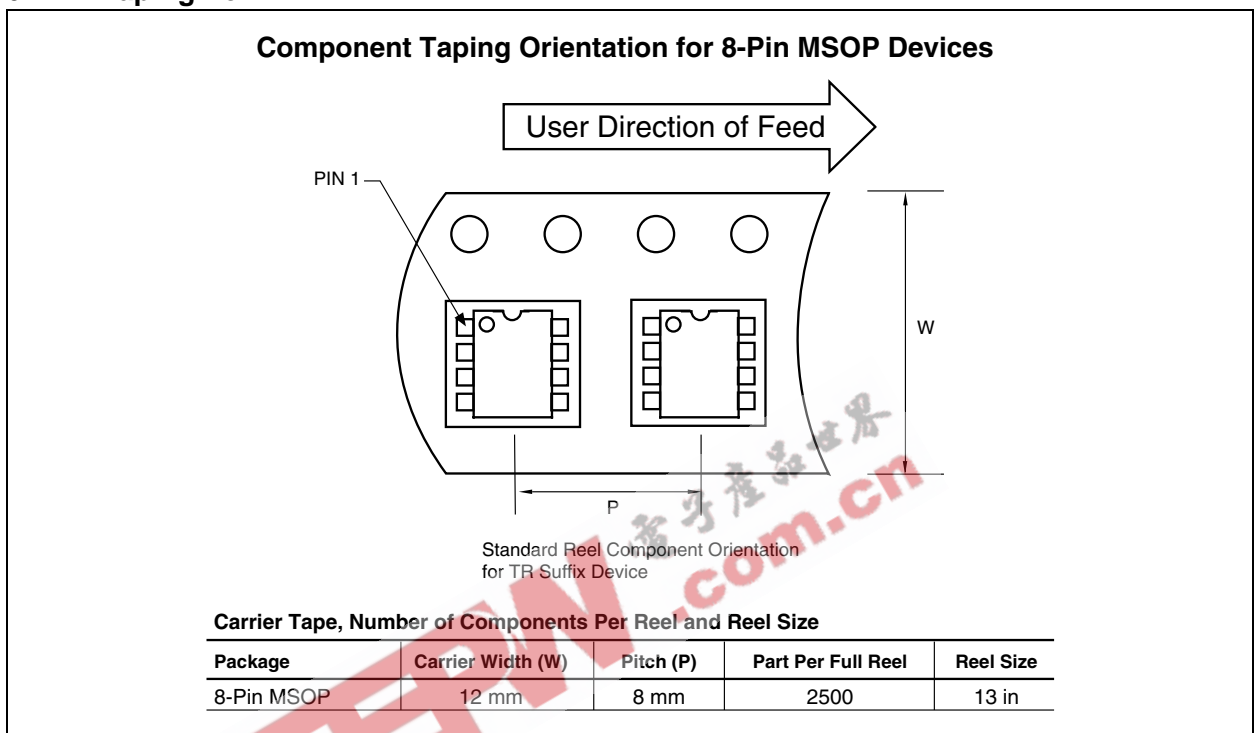


## 6.0 PACKAGING INFORMATION

### 6.1 Package Marking Information

Package marking data not available at this time.

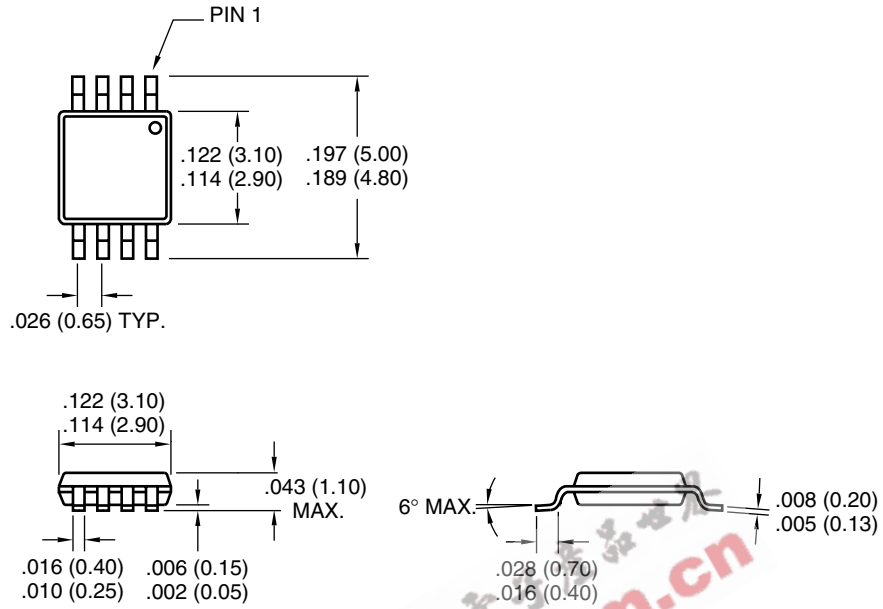
### 6.2 Taping Form



# TC1174

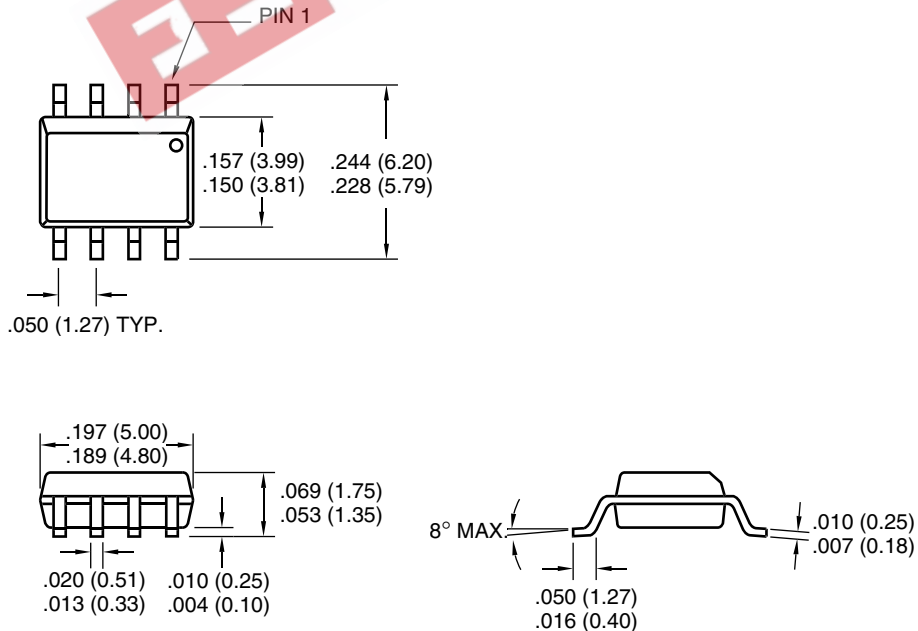
## 6.3 Package Dimensions

### 8-Pin MSOP



Dimensions: inches (mm)

### 8-Pin SOIC



Dimensions: inches (mm)



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# TC1174

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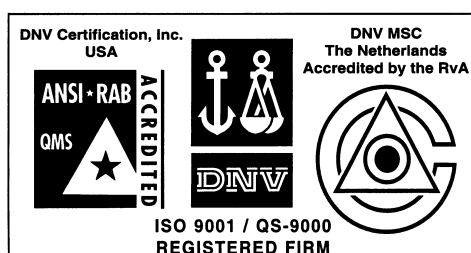
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Microchip Technology Inc.  
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San Jose, CA 95131  
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Mississauga, Ontario L4V 1X5, Canada  
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### ASIA/PACIFIC

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Microchip Technology Australia Pty Ltd  
Suite 22, 41 Rawson Street  
Epping 2121, NSW  
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Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

#### China - Beijing

Microchip Technology Consulting (Shanghai)  
Co., Ltd., Beijing Liaison Office  
Unit 915  
Bei Hai Wan Tai Bldg.  
No. 6 Chaoyangmen Beidajie  
Beijing, 100027, No. China  
Tel: 86-10-85282100 Fax: 86-10-85282104

#### China - Chengdu

Microchip Technology Consulting (Shanghai)  
Co., Ltd., Chengdu Liaison Office  
Rm. 2401, 24th Floor,  
Ming Xing Financial Tower  
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Microchip Technology Hongkong Ltd.  
Unit 901-6, Tower 2, Metroplaza  
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#### India

Microchip Technology Inc.  
India Liaison Office  
Divyasree Chambers  
1 Floor, Wing A (A3/A4)  
No. 11, O'Shaughnessey Road  
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Kanagawa, 222-0033, Japan  
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Microchip Technology Korea  
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Samsung-Dong, Kangnam-Ku  
Seoul, Korea 135-882  
Tel: 82-2-554-7200 Fax: 82-2-558-5934

### Singapore

Microchip Technology Singapore Pte Ltd.  
200 Middle Road  
#07-02 Prime Centre  
Singapore, 188980  
Tel: 65-6334-8870 Fax: 65-6334-8850

### Taiwan

Microchip Technology Taiwan  
11F-3, No. 207  
Tung Hua North Road  
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D-81739 Munich, Germany  
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Milan, Italy  
Tel: 39-039-65791-1 Fax: 39-039-6899883

#### United Kingdom

Microchip Ltd.  
505 Eskdale Road  
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Wokingham  
Berkshire, England RG41 5TU  
Tel: 44 118 921 5869 Fax: 44-118 921-5820

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